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METHOD FOR IMPROVING ADHESION TO COPPER

Abstract

Poorly adherent layers (5) such as silicon nitride and silicon dioxide exhibit improved adhesion to copper member (1) by providing an intervening germanium-containing layer (3). The germanium-containing layer (3) is copper germanide, germanium oxide, germanium nitride or combinations thereof. The germanium-containing layer (3) enhances the adhesion such that the poorly adherent layer (5) is less susceptible to delamination from the copper member (1).

Fig 1

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